

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
24 June 2004 (24.06.2004)

PCT

(10) International Publication Number
WO 2004/053968 A1

(51) International Patent Classification⁷: **H01L 21/304**

(21) International Application Number:
PCT/KR2003/001532

(22) International Filing Date: 30 July 2003 (30.07.2003)

(25) Filing Language: Korean

(26) Publication Language: English

(30) Priority Data:
10-2002-0077860
9 December 2002 (09.12.2002) KR

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(81) Designated States (*national*): CN, JP, US.

(84) Designated States (*regional*): European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR).

Published:

— with international search report

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: SLURRY COMPOSITION FOR SECONDARY POLISHING OF SILICON WAFER

(57) Abstract: Disclosed is a slurry composition for secondary polishing of silicon wafers comprising: 2 ~ 10 weight% of colloidal silica having an average particle size of 30 ~ 80 nm; 0.5 ~ 1.5 % by weight of ammonia; 0.2 ~ 1 weight% of a hydroxyalkylcellulose-based polymer for modifying rheology of the composition; 0.03 ~ 0.5 weight% of a polyoxyethylenealkylamine ether-based nonionic surfactant; 0.01 ~ 1 weight% of a quaternary ammonium base and the balance of deionized water.

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